Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
Li	6421	(257/686,704,706,707,713,723, 777).ccls.	US-PGPUB; USPAT	OR	OFF	2005/09/09 15:52
L2	2008	(361/719,720,780,794).ccls.	US-PGPUB; USPAT	OR	OFF	2005/09/09 15:52
L3	390	174/252.ccls.	US-PGPUB; USPAT	OR	OFF	2005/09/09 15:53
L4	8270	123	US-PGPUB; USPAT	OR	OFF	2005/09/09 15:53
L5	399	4 and @pd>="20050513"	US-PGPUB; USPAT	OR	OFF	2005/09/09 15:53
L6	15	5 and stiffen\$3	US-PGPUB; USPAT	OR	OFF	2005/09/09 15:59
L7	384	5 not 6	US-PGPUB; USPAT	OR	OFF	2005/09/09 15:59
L8	153	7 and stack\$3	US-PGPUB; USPAT	OR	OFF	2005/09/09 16:07
L9	231	7 not 8	US-PGPUB; USPAT	OR	OFF	2005/09/09 16:16
L10	1820	(257/686,704,706,707,713,723, 777).ccls.	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 16:28
111	174	(361/719,720,780,794).ccls.	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 16:28
L12	. 114	174/252.ccls.	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 16:28
L13	2086	10 11 12	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 16:28
L14	4	13 and stiffen\$3	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 16:29
L15	2082	13 not 14	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 16:29
L16	149	15 and stack\$3	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 16:41

L17	1933	15 not 16	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 16:42
L18	245	17 and (lid cover)	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 16:59
L19	1688	17 not 18	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 17:03
L20	2472	(438/109,122,125).ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 17:04
L21	86	20 and stiffen\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 17:05
L22	85	21 not 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 17:11
L23 ◆	2386	20 not 21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 17:11
L24	1027	23 and (lid cover)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 17:12
L25	656	24 and (asic memory (wire\$1 near2 bond\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 18:04

L26	287	25 and stack\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 17:24
L27	369	25 not 26	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 17:25
L28	371	24 not 25	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 18:04
L29	283	28 and heat	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 18:19
L30 _.	88	28 not 29	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 18:22
L31	1359	23 not 24	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 18:23
L32	11429	4 13 31	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 18:24
L33	702	32 and (reinforcement reinforce\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 18:25

L34	559	33 and heat	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 18:26
L35	512	34 not (5 14 16 18 22 24)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 18:28
L36	149	35 and (asic memory)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 19:00
L37	363	35 not 36	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 19:01
L38	94	37 and stack\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 19:04
L39	269	37 not 38	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/09 19:13

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	933	((stack\$3 with chip\$1 IC (integrated adj circuit\$1) asic\$1 memory semiconductor\$1) and (stiffen\$3 reinforc\$5)).clm.	US-PGPUB	OR	OFF	2005/09/09 19:25
L2	11	((stack\$3 with (chip\$1 IC (integrated adj circuit\$1) asic\$1 memory semiconductor\$1)) and (stiffen\$3 reinforc\$5) and (heat thermal)).clm.	US-PGPUB	OR	OFF	2005/09/09 19:31
L3	709	((stack\$3 with (chip\$1 IC (integrated adj circuit\$1) asic\$1 memory semiconductor\$1)) and (heat thermal)).clm.	US-PGPUB	OR	OFF	2005/09/09 19:31
L4	103	((stack\$3 with (chip\$1 IC (integrated adj circuit\$1) asic\$1 memory semiconductor\$1)) and (heat with (sink\$1 spreader\$1))). clm.	US-PGPUB	OR	OFF	2005/09/09 19:56
L5	44	((stack\$3 with (chip\$1 IC (integrated adj circuit\$1) asic\$1 memory semiconductor\$1)) and (heat with dissipat\$3)).clm.	US-PGPUB	OR	OFF	2005/09/09 20:00

Interference Search History